

Specification of Thermoelectric Module

TEFC1-05535

Description

The 55 couples, 7 mm × 15 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70°C, designed for superior cooling and heating up to 100 °C /200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

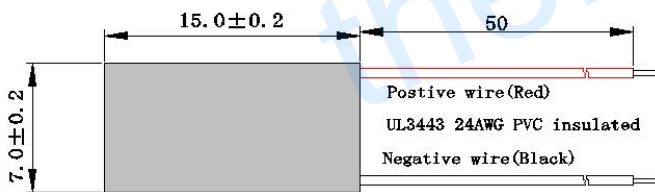
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

| | | | |
|----------------------------|------|------|---|
| Th (°C) | 27 | 50 | Hot side temperature at environment: dry air, N ₂ |
| DT _{max} (°C) | 70 | 79 | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U _{max} (Voltage) | 6.82 | 7.37 | Voltage applied to the module at DT _{max} |
| I _{max} (amps) | 3.46 | 3.46 | DC current through the modules at DT _{max} |
| Q _{Cmax} (Watts) | 15.2 | 16.4 | Cooling capacity at cold side of the module under DT=0 °C |
| AC resistance (ohms) | 1.50 | 1.62 | The module resistance is tested under AC |
| Tolerance (%) | 10% | | For thermal and electricity parameters |

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

B. Sealant:

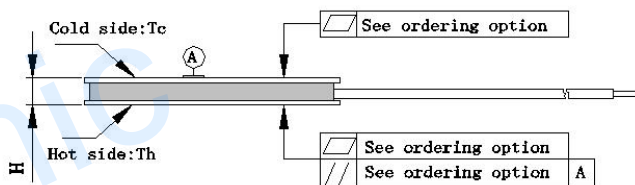
1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized



Ordering Option

| Suffix | Thickness H (mm) | Flatness/ Parallelism (mm) | Lead wire length(mm) Standard/Optional length |
|--------|------------------|----------------------------|--|
| TF | 0: 1.6±0.10 | 0: 0.05/0.05 | 50±3/Specify |
| TF | 1: 1.6±0.03 | 1: 0.02/0.02 | 50±3/Specify |

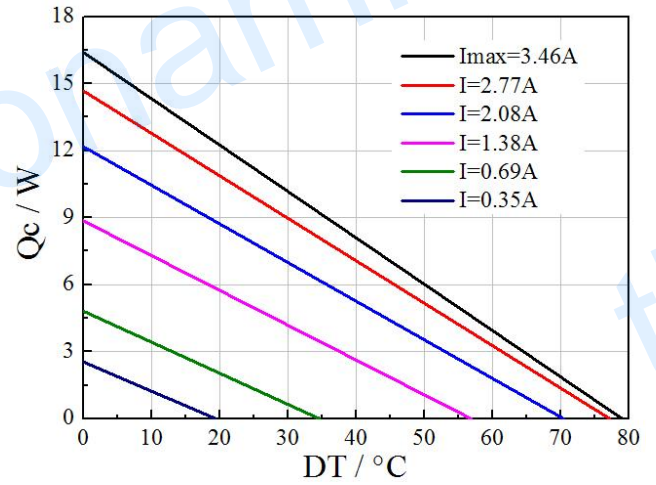
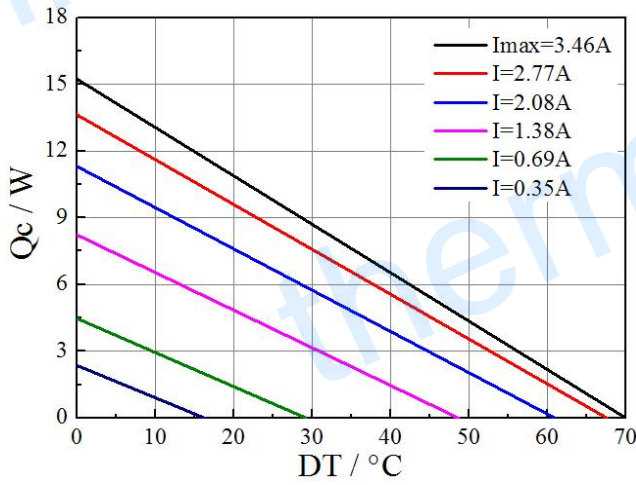
Eg. TF01: Thickness 1.6± 0.10 (mm) and Flatness 0.02 / 0.02(mm)

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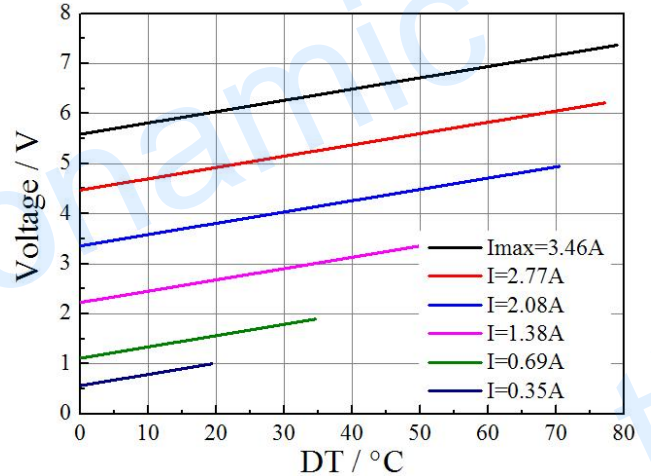
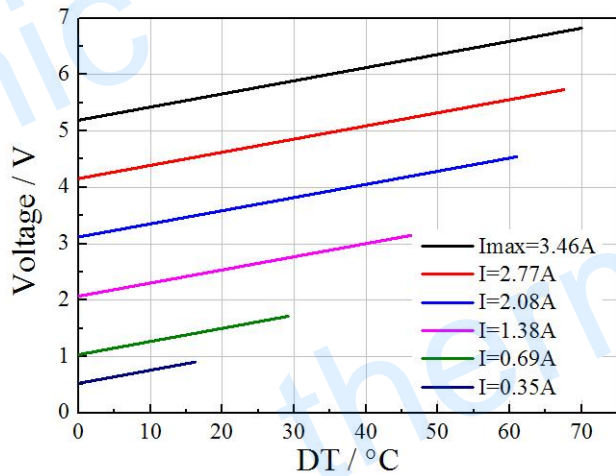
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Performance Curves at Th=27 °C

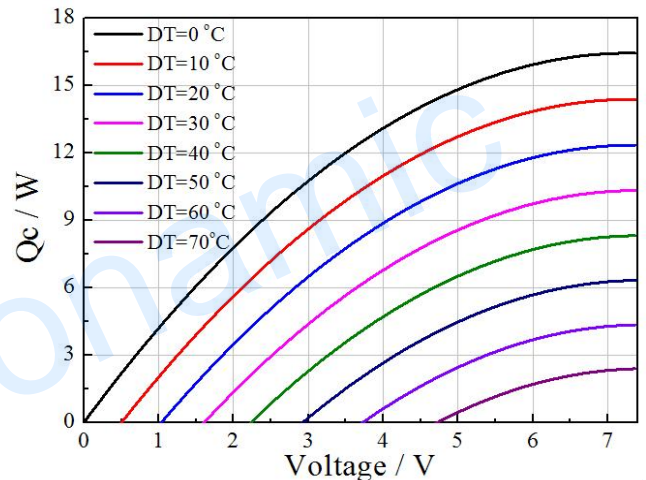
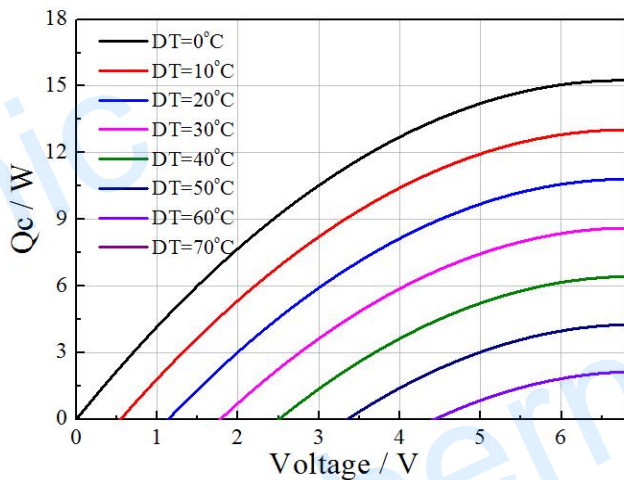
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

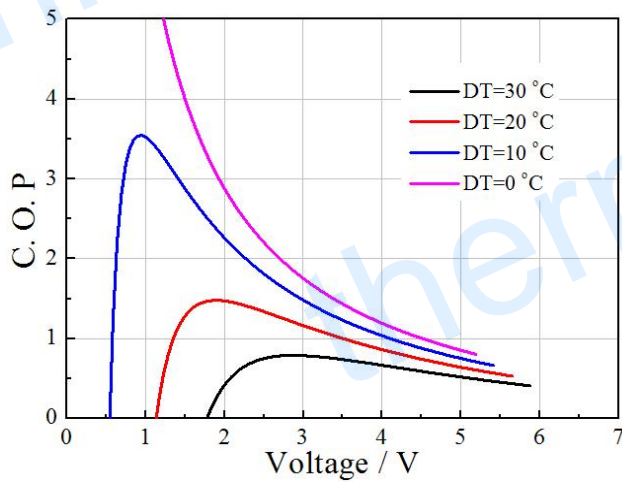


Standard Performance Graph $Q_c = f(V)$

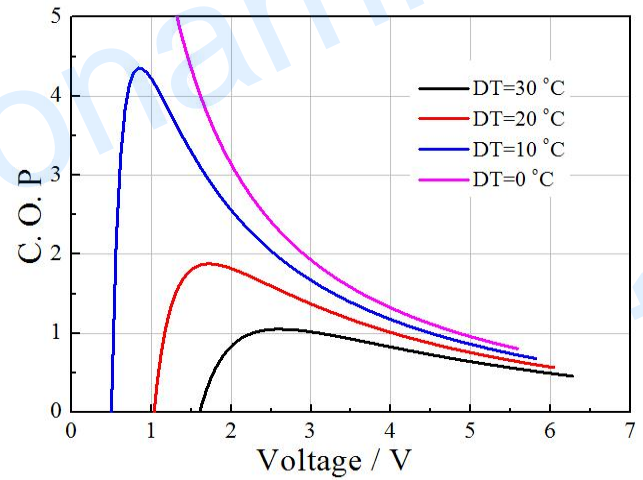
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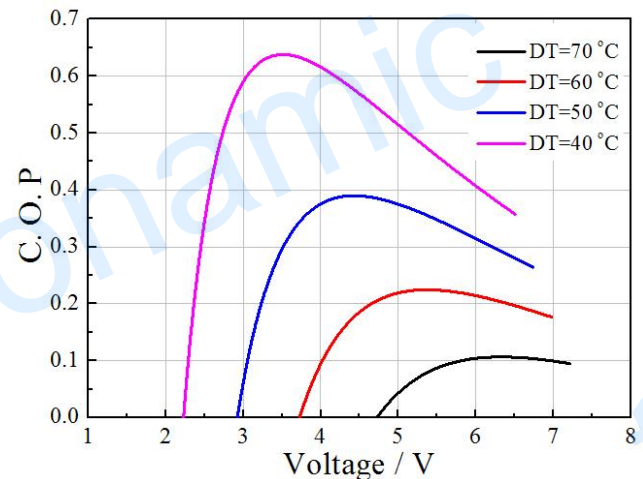
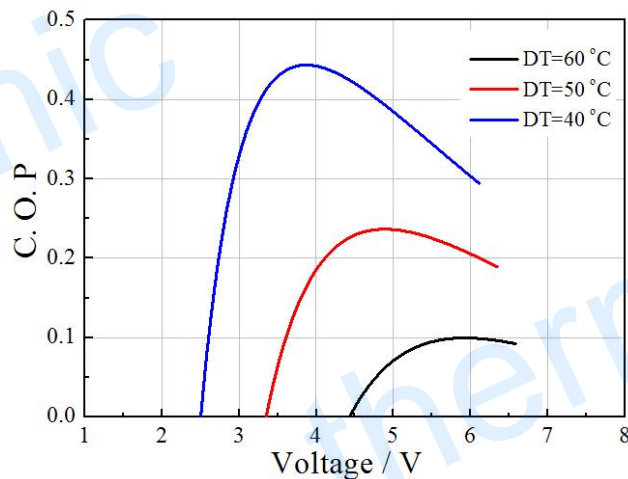
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.